



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-05-09
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	7NC5*Z70P83R	A	ZA41	2014-05-09
Amount	UoM	Unit type	ST ECOPACK Grade	
35.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFJ	4.14,2.76,1.94	1	J bend	
Comment	SMA Flat 2 Leads No exposed pad; MD valid for CP : STPS3170AF.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	7NC5*270P83R					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	1.384	mg	supplier	Die	Silicon (Si)	7440-21-3		1.323	mg	955925	37800
Silicon die				supplier	metallization	Aluminium (Al)	7429-90-5		0.01	mg	7225	286
Silicon die				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	723	29
Silicon die				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	1445	57
Silicon die				supplier	metallization	Nickel (Ni)	7440-02-0		0.007	mg	5058	200
Silicon die				supplier	metallization	Gold (Au)	7440-57-5		0.007	mg	5058	200
Silicon die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.009	mg	6503	257
Silicon die				supplier	back metallization	Gold (Au)	7440-57-5		0.002	mg	1445	57
Silicon die				supplier	back metallization	Nickel (Ni)	7440-02-0		0.011	mg	7948	314
Silicon die				supplier	passivation	Esterified polyamid	63428-83-1		0.01	mg	7225	286
Silicon die				supplier	passivation	Tetraethylene glycol dimethacrylate	109-17-1		0.001	mg	723	29
Leadframe	Copper & its alloys	14.947	mg	supplier	Frame Alloy	Cu	7440-50-8		14.925	mg	998528	426429
Leadframe				supplier	Frame Alloy	Fe	7439-89-6		0.015	mg	1004	429
Leadframe				supplier	Frame Alloy	P	7723-14-0		0.007	mg	468	200
Die attach	Other Organic Materials	2.573	mg	supplier	soft solder	Pb	7439-92-1	7a-Lead in high me	2.38	mg	924990	68000
Die attach				supplier	soft solder	Sn	7440-31-5		0.129	mg	50136	3686
Die attach				supplier	soft solder	Ag	7440-22-4		0.064	mg	24874	1829
Encapsulation	Other inorganic materials	15.469	mg	supplier	Moulding Compound	Silica , amorphous,fused	60676-86-0		12.375	mg	799987	353571
Encapsulation				supplier	Moulding Compound	Epoxy resin proprietare,resin unknow	29690-82-2		2.088	mg	134980	59657
Encapsulation				supplier	Moulding Compound	Benzophenone teracarboxylic anhydride	2421-28-5		0.155	mg	10020	4429
Encapsulation				supplier	Moulding Compound	Silica, quartz	14808-60-7		0.696	mg	44993	19886
Encapsulation				supplier	Moulding Compound	Carbon black	1333-86-4		0.155	mg	10020	4429
Finishing	Solder	0.627	mg	supplier	Connection Coating	Sn	7440-31-5		0.627	mg	1000000	17914